

Vin = 18V-20VDC

48Vout @ 3A

Copper trace is cut on board (disconnected).

NOTE2: Rx1, Rx2, and Rx3 can be replaced by using a single 1.74Kohm resistor rated at 1W.

NOTE1: All component designators with "x" suffix were added in the circuit as a modification to the original design and the PCB does not have placeholders for these components. R2 is not populated, and instead is shorted across its terminals.

PCB LOGO DANGER HIGH VOLTAGE

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Designed for: Public Release		Mod. Date: 3/24/2015	
Project Title: Single-Phase Synchronous Boost		Sheet Title: 1 Ch Boost Converter	
SVCN Rev: Not in version control		Assembly Variant: 001	
Drawn By: bkinsc		File: PMP9393 Schematics.SchDoc	
Engineer: Hrag Kasparian		Contact: http://www.ti.com/support	
Number: PMP9393	Rev: 0	Sheet: 1 of 2	Size: B



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H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

H5 1902C H6 1902C H7 1902C H8 1902C

H9 DNP H10 DNP H11 DNP H12 DNP

DNP FID1 DNP FID2 DNP FID3

PCB Assembly
PMP7950 Rev1B

PCB
LOGO
Texas Instruments

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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